

CLAIMS

1. A holding structure for an electronic part, including a first resin mold which has a positioning shape portion for the electronic part, and a second resin mold which is insert-molded so as to cover the first resin mold and the electronic part positioned with the first resin mold, characterized in that

said positioning shape portion of said first resin mold is provided with a through hole for allowing an insert resin material to pass therein to form the second resin mold.

2. A holding structure for an electronic part, as claimed in claim 1, wherein said positioning shape portion has a cup-shaped configuration in which the electronic part is adapted to be inserted.

3. A holding structure for an electronic part, as claimed in claim 2, wherein said through hole is provided in a bottom wall of said positioning shape portion.

4. A holding structure for an electronic part, as claimed in claim 3, wherein said through hole provided in said bottom wall of said positioning shape portion includes two through holes.

5. A holding structure for an electronic part, as claimed in claim 2, wherein said through hole is provided in a side wall of said positioning shape portion.

6. A holding structure for an electronic part, as claimed in claim 3, wherein said through hole provided in said side wall of said positioning shape portion

includes two through holes.

7. A holding structure for an electronic part, as claimed in claim 1, wherein a gap is provided between an inner wall surface of said positioning shape portion with a cup-shaped configuration, in which the electronic part is adapted to be inserted, and the electronic part.

8. A holding structure for an electronic part, as claimed in claim 1, wherein said through hole guides said insert resin material to form said second resin mold into said positioning shape portion.